



YAMAUCHI Re-usable Cushion Pad

Line-up of cushion pad

J-LAG01

Application : Heat lag for Pin-lamination outside of pin-tolls.
 Thermal resistance : Less than 230C (446F)
 Life target : Less than 200 cycles
 Max dimension : 1300 x 3200mm (51" x 125")



YOM Series

Application : Main cushion for Pin / Pin-less lamination.
 Thermal resistance : Less than 250C (482F) with Top Plate
 Life target : Less than 500 cycles
 Max dimension : 1300 x 3200mm (51" x 125")
 Grade : YOM01,02,03,04 / VGR Surface, YOM-H & YOM-F series



YOM-Flex

Application : High conformity of direct cushion for FPC & R/F.
 Thermal resistance : Less than 210C (410F)
 Life target : Less than 100 cycles
 Max dimension : 730 x 730mm (28" x 28")



FB Series

Application : Stable conformity of direct cushion for FPC & R/F.
 Thermal resistance : FB <230C (450F) FF,TB317K <210C(410F)
 Life target : Less than 300 cycles
 Max dimension : 750 x 750mm (29" x 29") for FB Series
 Grade : FB Series + TB317K & FF10N



STB-3R/TB-557

Application : High temperature cushion for Rigid & bonding.
 Max 300C (572F) for TB-557 & Max 400C (752F) for STB-3R
 Life target : Less than 50 cycles
 Max dimension : 1300x3200mm (51" x 125")

